



DirectFET Small Can

RoHS Compliance Document

Contents:

1. Composition
2. Solder Reflow

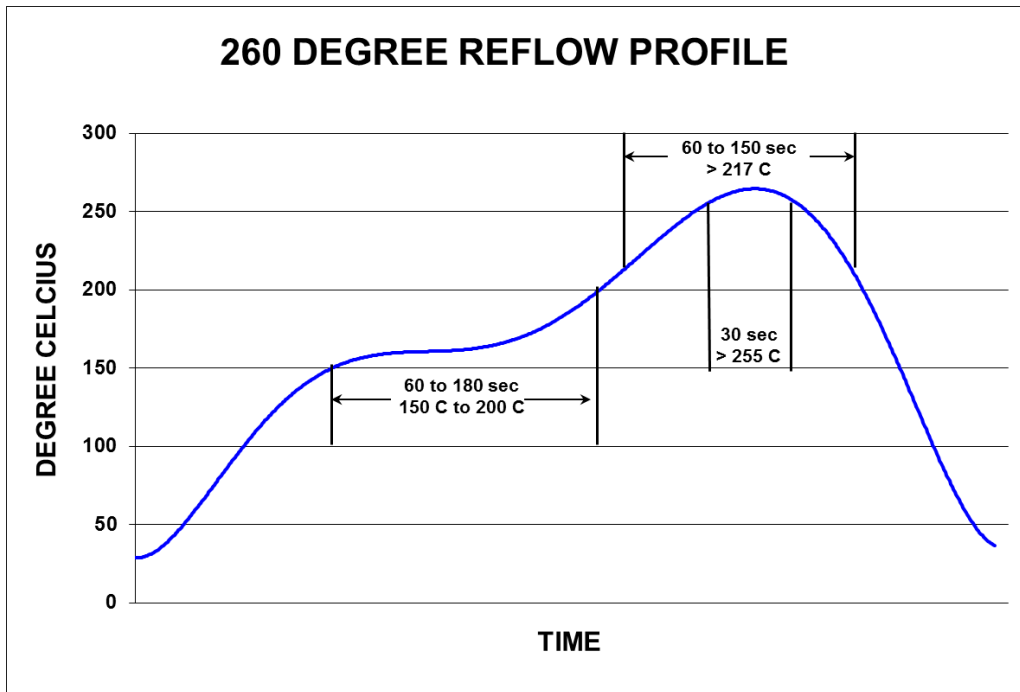


DirectFET - Small Can

Component	Material Name	Material Mass (g)	Element Name Composition	CAS #	Substance Mass (g)	Material Analysis Weight (%)	% of Total Weight
Chip	Silicon	0.00332	Si	7440-21-3	0.00316	95%	6.6%
			Epoxy	90598-46-2	0.00016	5%	0.3%
Lead Frame	Plated Copper	0.04304	Cu	7440-50-8	0.04190	97%	87.0%
			Ni	7440-02-0	0.00026	1%	0.5%
			Ag	7440-22-4	0.00088	2%	1.8%
Die Attach	Silver Epoxy	0.00101	Ag	7440-22-4	0.00076	75%	1.6%
			Epoxy	90598-46-2	0.00025	25%	0.5%
Solder	Solder Bumps	0.00080	Sn	7440-31-5	0.00074	93%	1.6%
			Ag	7440-22-4	0.00005	6%	0.1%
			Cu	7440-50-8	0.00001	1%	0.0%

Total Weight (g) **0.04817**

No tin whisker mitigation strategy



This part is compliant with EU Directive 2011/65/EU (RoHS Directive) and does not contain lead, mercury, cadmium (0.01%), hexavalent chromium, PBB or PBDE in concentrations greater than 0.1%, except as permitted by Annex III. Further part complies with 3 reflow cycles per JEDEC J-STD-020